ABSTRACT

PROCESS TREATING MEMBER, SUBSTRATE TREATING APPARATUS INCLUDING THE MEMBER, AND SUBSTRATE TREATING METHOD USING THE APPARATUS

A substrate treating apparatus includes an inner chamber in which a first space is formed, a first outer chamber surrounding the inner chamber and forming a second space separated from the first space, a susceptor disposed in the first space and adapted to support a substrate, a first exhaust line connected to the inner chamber and exhausting a gas in the first space to the outside, a process gas supply member adapted to supply a process gas for treating the substrate to the first space, and a monitor module disposed in the second space and adapted to monitor a state of the first space.

(Fig. 1)